

REMARKS

New claim limitations are presented, whereby the next Action cannot be final.

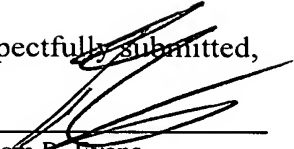
The last, final Action rejected independent Claim 1 and, thus, the other dependent claims under 35 USC 103 (a) as obvious from the Applicant Admitted Prior Art (APA). The Action found the difference between Claim 1 and the APA was only the obtuse angle θ between the positioning pin and the receiving part. This rejection is traversed for the following reasons.

In the APA, the first prior art reference of FIG. 1 disclosed a right angle or acute angle between the positioning pin 13 and the receiving part 12, and a plane of the positioning pin 13 is abutted against the entire side surface of the substrate 5. The second prior art reference of FIG. 2 disclosed an arched positioning pin 23. A plane of the positioning pin 23 facing the semiconductor encapsulant package is curved (not slanted), and the plane of the positioning pin 23 is only abutted against a top edge of the side surface of the substrate 5.

In comparison, in the amended Claim 1, taking FIG. 3 for example, a first plane of the positioning pin 331 facing the semiconductor encapsulant package is slanted, so that the first plane of the positioning pin 331 is only abutted against a lower edge of the side surface of the substrate 5. Therefore, only the structure of amended Claim 1 can overcome the problems of glue leaking along the positioning pin to the backside of the substrate and the receiving part more effectively. Accordingly, the APA does not make claim 1 obvious.

Reconsideration and allowance are, therefore, requested.

Respectfully submitted,



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